

HAYNES BEFFEL & WOLFELD LLP

INTELLECTUAL PROPERTY LAW

P.O. Box 366, 751 Kelly Street

Half Moon Bay, CA 94019

Phone 650-712-0340 Fax 650-712-0263

www.HMBay.com

MARK HAYNES
FRNIE BEFFEL
WARREN WOLFELD*Of Counsel*
JIM HANNS
*BILL KENNEDY

*admitted in MA only

ERIC AMADOR
Registered Patent Agent**FACSIMILE TRANSMITTAL FORM**

FAX NUMBER:	(703) 308-7722
TRANSMITTED TO:	Examiner Hsien Ming LEE, Art Unit 2823
OF:	United States Patent and Trademark Office
FROM:	Bill Kennedy, Reg. No. 33,407
CLIENT/MATTER:	CPAC 1003-1 (09/802,664)
DATE:	14 MARCH 2003

TOTAL NUMBER OF PAGES INCLUDING THIS COVER SHEET: 4

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TECHNOLOGY CENTER 2800

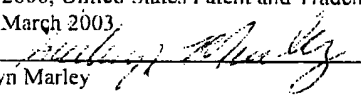
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Attorney Docket No. CPAC 1003-1

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to TC 2800, United States Patent and Trademark Office at Fax No. (703) 308-7722
on 14 March 2003.


Kathryn Marley

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Rajendra D. PENDSE

Group Art Unit: 2823

Application No. 09/802,664

Examiner: Hsien Ming LEE

Filed: 9 March 2001

CUSTOMER NO. 22470

Title: Flip Chip Interconnection Structure

Commissioner for Patents
Washington, D.C. 20231

Sir:

TRANSMITTAL OF AMENDMENT/RESPONSE

In connection with the above-referenced U.S. patent application, transmitted herewith are the following papers:

- ☒ Second Preliminary Amendment.
☒ A fee for amendment of claims is required, and is calculated as shown below:

AMENDED CLAIMS					
	NO. OF CLAIMS	HIGHEST NO. OF CLAIMS PREVIOUSLY PAID FOR	EXTRA CLAIMS	LARGE ENTITY RATE	ADDITIONAL FEE
Total Claims	21	- 20	1	x \$18 =	\$ 18.00
Independent Claims	2	- 3	=	x \$84 =	\$
If Amendment adds multiple dependent claims, add \$260.00					\$
Total Amendment Fee (LARGE ENTITY)					\$ 18.00
If small entity status is claimed, subtract 50% of Total Amendment Fee					
FEE DUE FOR AMENDMENT OF CLAIMS FOR THIS RESPONSE					\$18.00

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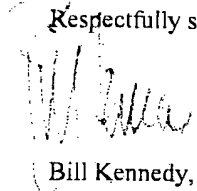
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The Commissioner is hereby authorized to charge \$18.00 to our Deposit Account No. 50-0869 (CPAC 1003-1).

The Commissioner is hereby authorized to charge any additional fees under 37 C.F.R. §§ 1.16 and 1.17 that may be required by this paper, and to credit any overpayment, to Deposit Account No. 50-0869 (CPAC 1003-1).

Respectfully submitted,

Date: 14 March 2003

 Reg. No. 33,407
Bill Kennedy, Reg. No. 33,407

Haynes Beffel & Wolfeld LLP
P.O. Box 366
Half Moon Bay, CA 94019
(650) 712-0340 (telephone)
(650) 712-0263 (facsimile)

Atty. Docket No. CPAC 1023-1

PATENT

Appl. No. 09/802,664

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Rajendra D. PENDSE

Application No.: 09/802,664

Filed: March 9, 2001

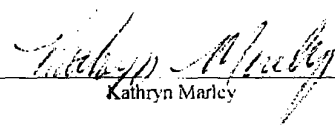
Title: **Flip chip interconnection structure**

)
) Examiner: Hsien Ming LEE
)
) Group Art Unit: 2823
)
) Date: March 14, 2003

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office, TC 2800 at fax no. 703 308-7722 on March 14, 2003.

Signed


Kathryn Marley

COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SECOND PRELIMINARY AMENDMENT

Dear Sir:

Preliminarily, kindly amend the application as follows:

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In the claims:

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Please add the following new claims:

18. The method of claim 1 wherein a width of the second member is smaller than a width of the first member.

19. The method of claim 1 wherein the second member has a generally trapezoidal shape in transverse sectional view, and includes a plateau having a width smaller than a width of the first member.

20. The method of claim 1, further comprising, prior to pressing the first and second members against one another, dispensing a curable adhesive onto a mating surface of the substrate.